

**FEATURES:**

- Reverse Voltage - 40 to 200 V
- Forward Current - 1 A
- High Surge Current Capability
- Designed for Surface Mount Application

**MECHANICAL DATA**

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0024oz

**PINNING**

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )



MBF Package

**Maximum Ratings and Electrical characteristics**

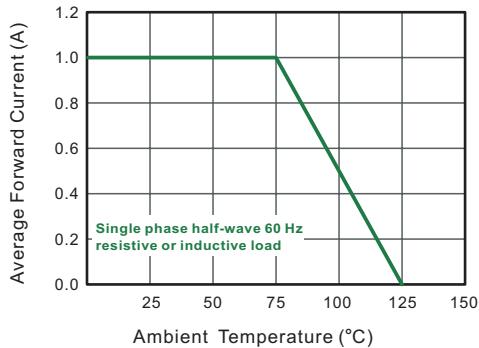
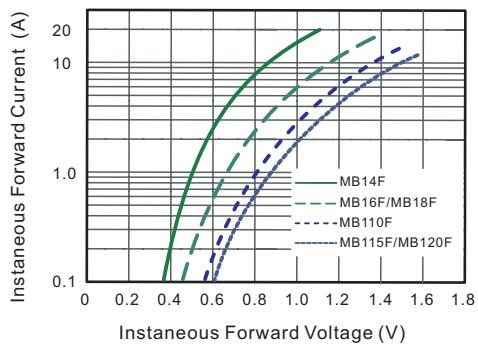
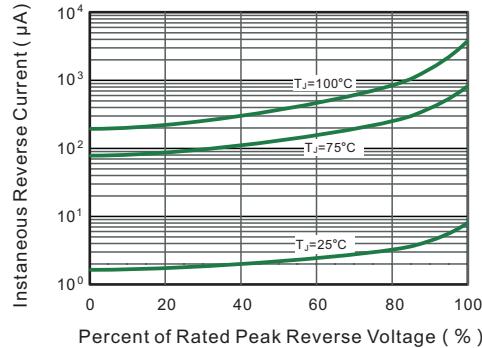
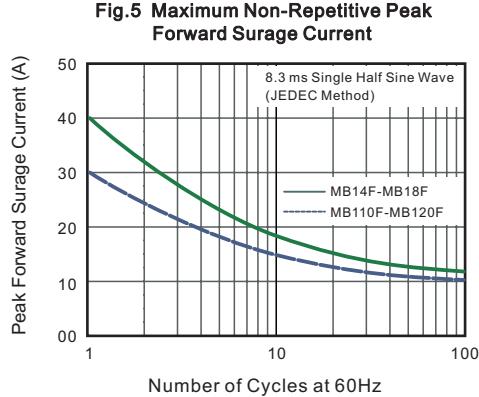
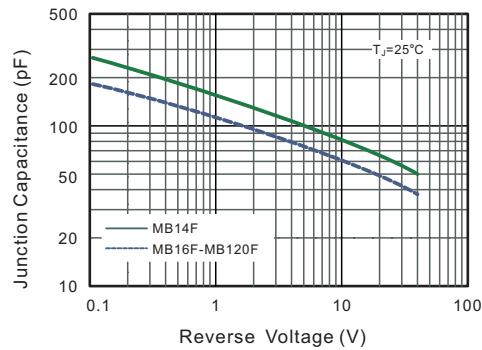
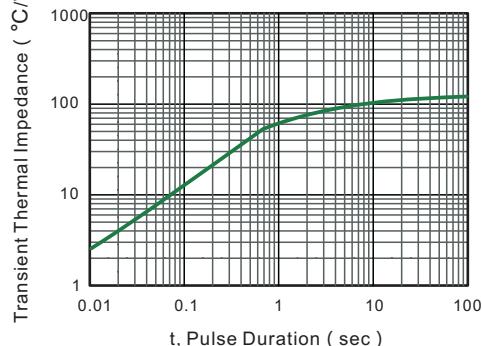
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB14F	MB16F	MB18F	MB110F	MB115F	MB120F	Units						
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	40	60	80	100	150	200	V						
Maximum RMS voltage	V <sub>RMS</sub>	28	42	56	70	105	140	V						
Maximum DC Blocking Voltage	V <sub>DC</sub>	40	60	80	100	150	200	V						
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	1.0						A						
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	40			30			A						
Max Instantaneous Forward Voltage at 1 A	V <sub>F</sub>	0.50	0.70	0.85	0.90			V						
Maximum DC Reverse Current T <sub>a</sub> = 25°C at Rated DC Reverse Voltage T <sub>a</sub> = 100°C	I <sub>R</sub>	0.3 10		0.2 5	0.1 2			mA						
Typical Junction Capacitance <sup>1)</sup>	C <sub>j</sub>	110	80					pF						
Typical Thermal Resistance <sup>2)</sup>	R <sub>θJA</sub>	115						°C/W						
Operating Junction Temperature Range	T <sub>j</sub>	-55 ~ +125						°C						
Storage Temperature Range	T <sub>stg</sub>	-55 ~ +150						°C						

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

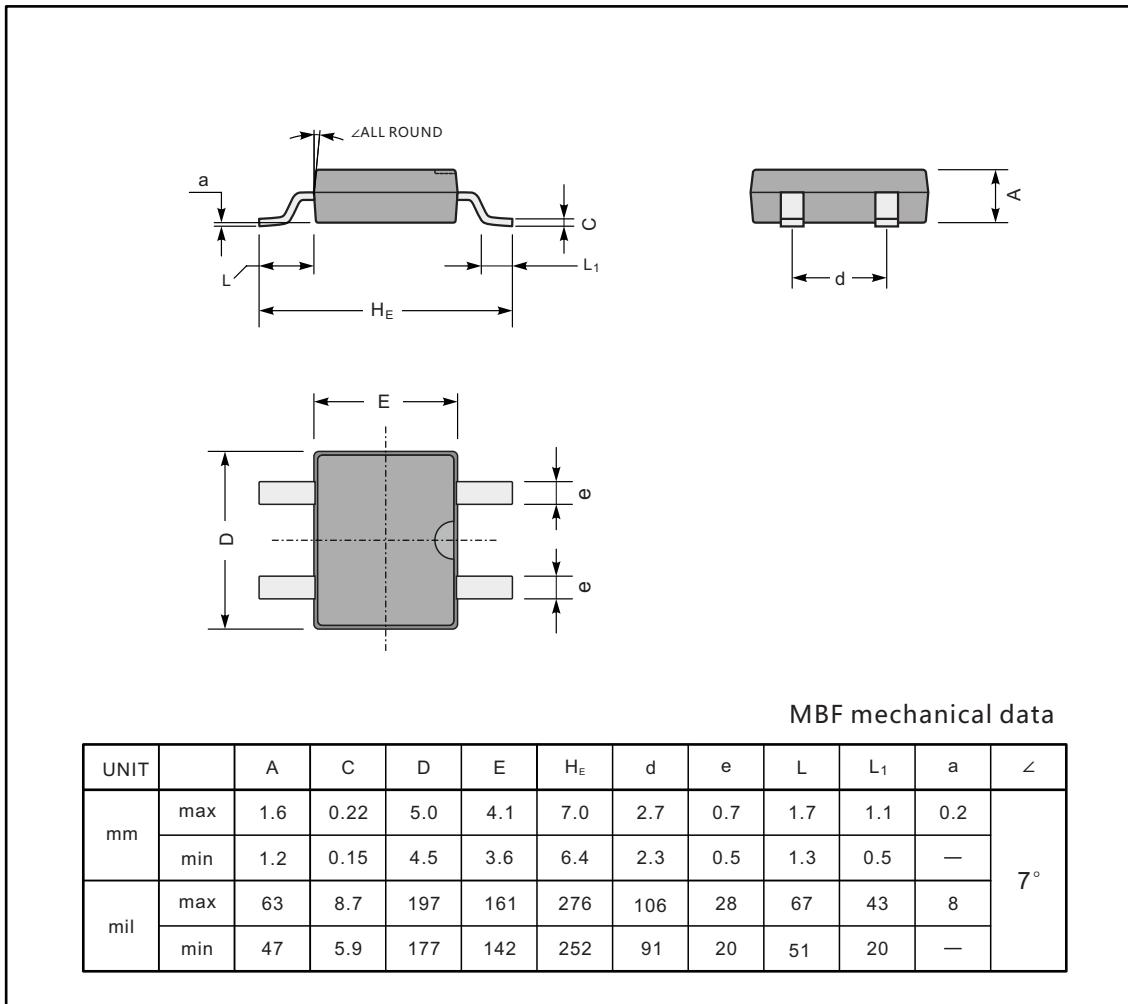
 2. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> copper pad.

**Fig.1 Forward Current Derating Curve**

**Fig.2 Typical Reverse Characteristics**

**Fig.4 Typical Junction Capacitance**

**Fig.6- Typical Transient Thermal Impedance**


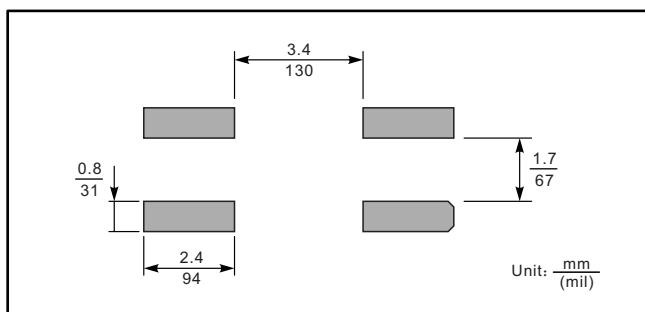
## PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

**MBF**



### The recommended mounting pad size



### Marking

Type number	Marking code
MB14F	MB14F
MB16F	MB16F
MB18F	MB18F
MB110F	MB110F
MB115F	MB115F
MB120F	MB120F

